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Agenda



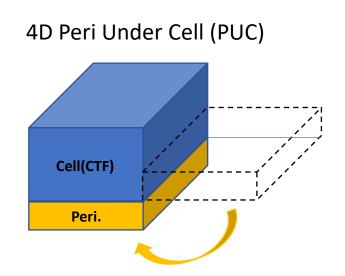
- SK Hynix NAND Tech Platform Scaling
- Challenges of Stacking
- Methods to Improve Program Efficiency
- Concept of a New Method to Improve Program Efficiency and Results
- Summary

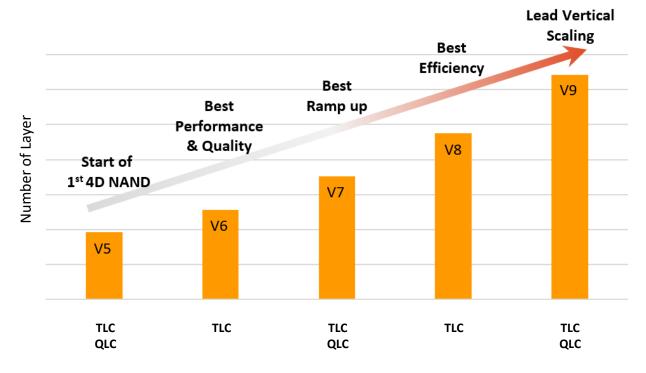


SK Hynix NAND Tech Platform Scaling



- SK Hynix's been mass-producing 4D PUC up to the 5th generation, utilizing highly matured CTF technology
- Also developed QLC NAND, starting with the first generation of 4D PUC





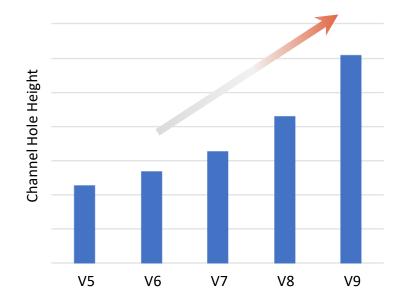


Challenges of Stacking

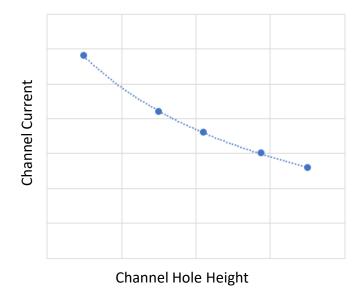


- The total height of the channel hole has increased with the addition of multiple layers
- To secure channel current, the vertical gate pitch should be reduced
 - → Cell characteristic will be deteriorated

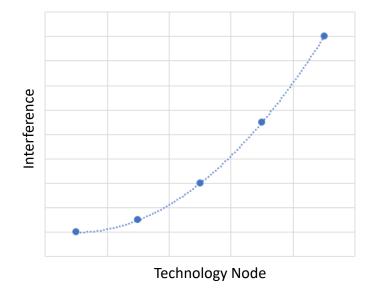
Channel Hole Height



Channel Current



Interference between word lines

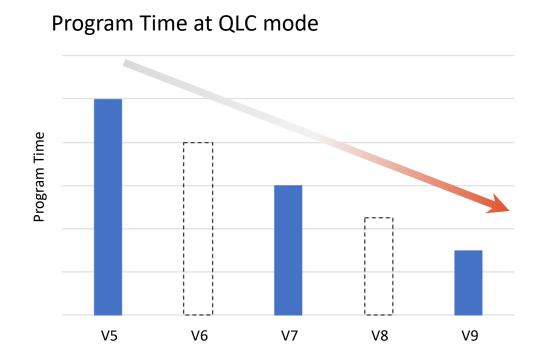




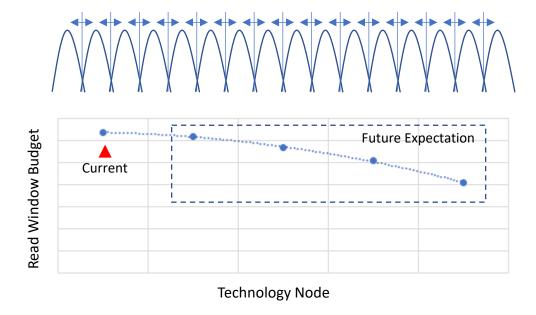
QLC Program Time and Read Window Expectation



- QLC program time is becoming shorter as generations progress
- Due to these circumstances, a reduction in the read window is anticipated in future tech.



Read Window Budget Expectation





Methods to Improve Program Efficiency



There are various approaches to improving program efficiency, but there are also challenges involved

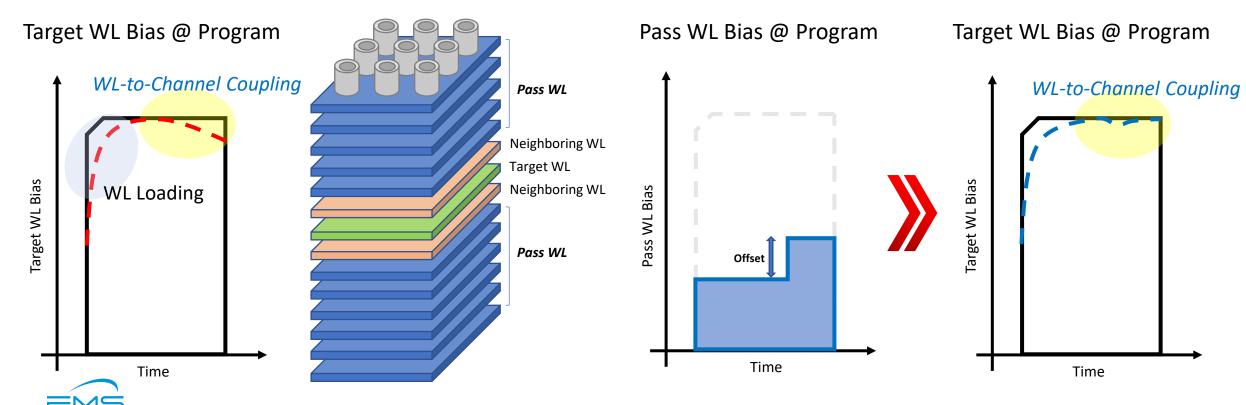
Program Efficiency Improvement Methods			Challenges	
Process	WL Resistivity Improvement		Cost, Vertical gate pitch	
Design	Pump Capacity/Efficiency		Chip Size, Power Consumption	
Algorithm	Program Net-time Control	ell	Program Disturbance Degradation	
	Program Pulse Bias Control		WL to WL Breakdown / WL to Channel Breakdown	Neighboring Cell Target Cell Neighboring Cell Blocking Layer CTN Tunneling Layer Channel
	Neighboring WL Control Neighboring Layer CTN Tunneling Layer Channel		Lateral Charge Spreading	Neighboring Cell Target Cell Neighboring Cell Space Space Blocking Layer CTN Tunneling Layer Channel

Another Way to Improve Program Efficiency

the Future of Memory and Storage



- Program efficiency has degraded due to word line (WL) loading and WL-to-Channel coupling
- WL-to-channel coupling is caused by the drop in channel potential during a program pulse
- To compensate for the WL-to-Channel coupling, the bias on the pass WLs needs to be offset at program pulse

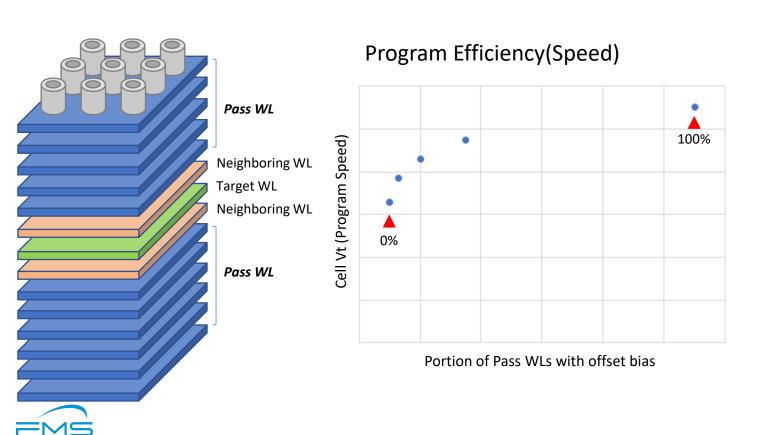


Results

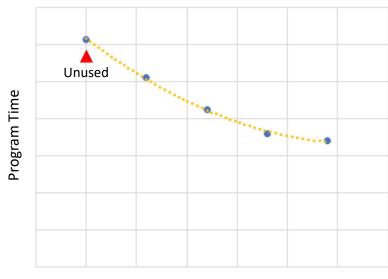
the Future of Memory and Storage



- Increasing the portion of Pass WL with applied offset bias enhances program efficiency
- As the offset bias is increased, the QLC program time decreases, and saturation is observed beyond a certain offset bias



QLC Program Time by Offset Bias



Pass WLs Offset Bias

Summary



- As more layers are introduced in NAND flash memory, reducing vertical gate pitch helps address channel current but may negatively impact cell characteristics and program performance
- Various methods are available to improve program efficiency, each with its own advantages and disadvantages
- One effective strategy is to adjust the bias of the Pass WLs during program operations
- Using this method, mitigate the effects of program efficiency reduction caused by WL-to-channel coupling



PGM Efficiency Improvement Method for QLC device

Questions?

Talk to us in the hallway or at the SK Hynix Booth!

